SURFBOARDS

THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TAM



33000 SERIES APPLICATION SPECIFIC ADAPTERS

IDS33110

MODEL

33110

10 LEAD .4 mm PITCH 4 SIDED DEVICES

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ACCEPTS

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PARTIAL LISTING

ANALOG

LFCSP UQ 1.3x1.6MM (CP-10-10)

FAIRCHILD

10LD UMLP, QUAD 1.4x1.8MM

ON SEMI

UQFN10 1.4x1.8,0.4P WQFN10 1.4x1.8,0.4P

Feature Pins on .1 in. Centers designed for use with Solderless breadboards, Conventional Breadboards, and Sockets with

Use For Prototyping, Device Test or Evaluation and SMD to Through Hole Conversion.

FIG.	MM	IN.	NOTE:	
Α	25.4	1.0	BOARD WIDTH +5mm .020in.	
В	10.16	.400	BOARD HEIGHT +5mm .020in.	
С	2.54	.100	SIP PIN SPACE +20mm .008in.	
D	2.3	.090	PAD CENTERLINE	
D1	1.88	.074	PAD CENTERLINE OTHER AXIS	
E	.4	.016	DEVICE LEAD PITCH	
F	1.3	.051	PAD LENGTH	
G	.225	.009	PAD WIDTH	
Н	.175	.007	GAP	
- 1	3.15	.124	MAX LEAD WIDTH	
l1	2.75	.108	MAX LEAD WIDTH OTHER AXIS	
J	1.8	.070	TYPICAL LEAD WIDTH	
J1	1.4	.055	TYPICAL LEAD WIDTH OTHER AXIS	
Р	3.3	.130	LENGTH FROM SHOULDER +5mm .020in.	
S	1.57	.062	PIN SHOULDER HEGHT	
W	.5	.020	PIN WIDTH	
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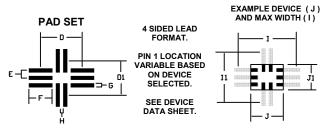
TEXAS INST. RSW (PUQFN-N10)

ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT

standard .1 in. centers.

FIG.	ММ	IN.	NOTE:	
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J	1.8	.070	TYPICAL LEAD WIDTH	
J1	1.4	.055	TYPICAL LEAD WIDTH OTHER AXIS	
Р	3.3	.130	LENGTH FROM SHOULDER +5mm .020in.	
S	1.57	.062	PIN SHOULDER HEGHT	
W	.5	.020	PIN WIDTH	
TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters.				

SINGLE-IN-LINE (SIP) PINS ON .100 in. CENTERS



MOUNTING PADS ARE OVERSIZED IN LENGTH TO ACCEPT A WIDER RANGE OF DEVICE WIDTHS AND TOLERANCES AND TO PERMIT HAND SOLDERING. SEE WEBSITE FOR SOLDERING SUGGESTIONS

BOARD SPECIFICATIONS

BOARD MATERIAL: .8mm, +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent.

CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +- .5mm .020in.

Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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